

## SELECTABLE GTL VOLTAGE REFERENCE

#### **FEATURES**

- V<sub>DD</sub> Range: 3.0 V to 3.6 V
   V<sub>TT</sub> Range: 1 V to 1.3 V
- Provides Selectable GTL V<sub>RFF</sub>
  - 0.615  $\times$  V<sub>TT</sub>
  - 0.63  $\times$  V<sub>TT</sub>
  - 0.65  $\times$  V<sub>TT</sub>
  - 0.67  $\times$  V<sub>TT</sub>
- ±1% Resistor Ratio Tolerance
- Ambient Temperature Range: –40°C to 85°C
- ESD Protection Exceeds the Following Levels Tests (Tested Per JESD-22):
  - 2500-V Human-Body Model (A114-B, Class II)
  - 250-V Machine Model (A115-A)
  - 1500-V Charged-Device Model (C101)

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## **DESCRIPTION/ORDERING INFORMATION**

The SN74GTL3004 provides for a selectable GTL Voltage Reference (GTL  $V_{REF}$ ). The value of the GTL  $V_{REF}$  can be adjusted using S0 and S1 select pins.

The S0 and S1 pins contain glitch-suppression circuitry for excellent noise immunity. When left floating, the S0 and S1 control input pins have  $100-k\Omega$  pullups that set the GTL  $V_{REF}$  default value to the  $0.67 \times V_{TT}$  ratio (S0 = 1 and S1 =1).

#### **ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE <sup>(1</sup>	)(2)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SOT (SC70) - DCK	Tape and reel	SN74GTL3004DCKR	2TK

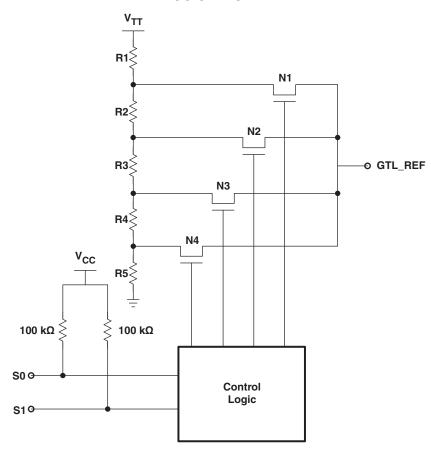
- 1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



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## **LOGIC DIAGRAM**



## **FUNCTION TABLE**

S1	S0	RATIO SET
0	0	$0.615 \times V_{TT}$
0	1	$0.63 \times V_{TT}$
1	0	$0.65 \times V_{TT}$
1	1	$0.67 \times V_{TT}$



## ABSOLUTE MINIMUM AND MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{DD}$	Power supply voltage range	-0.3	4.6	V	
V <sub>TT</sub>	Termination voltage range <sup>(2)</sup>	-0.3	4.6	V	
V <sub>IN</sub>	Control input voltage range (2)	-0.3	$V_{DD} + 0.3$	V	
V <sub>GTL_REF</sub>	Resistor output voltage range (2)	sistor output voltage range <sup>(2)</sup>			
I <sub>IK</sub>	Input clamp current	V <sub>IN</sub> < 0		-18	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-18	mA
	Continuous current through V <sub>DD</sub> or GND			100	mA
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>	DCK package		259	°C/W
T <sub>stg</sub>	Storage temperature range	-65	150	°C	

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### **RECOMMENDED OPERATING CONDITIONS(1)**

	PARAMETER	MIN	TYP	MAX	UNIT
$V_{DD}$	Power supply voltage	3	3.3	3.6	V
$V_{TT}$	Termination voltage	1	1.1	1.3	V
V <sub>IH</sub>	High-level control input voltage	V <sub>DD</sub> × 0.65			V
V <sub>IL</sub>	Low-level control input voltage			$V_{DD} \times 0.35$	V
VI	Control input voltage	0		$V_{DD}$	V
I <sub>OUT</sub>	I <sub>GTL_REF</sub> , GTL_REF output current		0	10	μΑ
PW	Control input pulse width	110			ns
T <sub>A</sub>	Operating free-air temperature	-40		85	°C

<sup>(1)</sup> All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow of Floating CMOS Inputs, literature number SCBA004.

#### **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range,  $T_A = -40$ °C to 85°C,  $V_{DD} = 3.3$  V ±10%, GND = 0 V (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{IK}$	Control	$V_{DD} = 3.6 \text{ V}, I_{IN} = -18 \text{ mA}$			-1.8	V
I <sub>IN</sub>	Control	$V_{DD} = 3.6 \text{ V}, V_{IN} = \text{GND}$			43	μΑ
I <sub>DD</sub>		$V_{DD} = 3.6 \text{ V}, V_{IN} = \text{GND}, I_{O} = 0 \text{ mA}$			85	μΑ
R	End-to-end resistance	V <sub>DD</sub> = 3.6 V, V <sub>TT</sub> = 1.1 V, I <sub>O</sub> = 0 mA	4.25	7.12	10.6	kΩ
	GTL V <sub>REF</sub> accuracy <sup>(1)</sup>	I <sub>O</sub> = 0 μA, See Figure 1	-1		1	%
	GTL V <sub>REF</sub> accuracy	I <sub>O</sub> = 10 μA, See Figure 1	-7		7	70

<sup>(1)</sup> GTL V<sub>REF</sub> accuracy is used to compare measured GTL\_VREF voltage versus expected GTL\_VREF voltage as determined by control inputs S0 and S1. The resistor ratio tolerance is incorporated into this parameter.

#### SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range,,  $T_A = -40^{\circ}\text{C}$  to 85°C,  $V_{DD} = 3.3 \text{ V} \pm 10\%$ , GND = 0 V (unless otherwise noted)

PARAMETER		PARAMETER TEST CONDITIONS			MAX	UNIT
PSR	Power supply rejection			-58		dB
	Pulse rejection				40	ns

Product Folder Link(s): SN74GTL3004

<sup>(2)</sup> The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>(3)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.



## PARAMETER MEASUREMENT INFORMATION

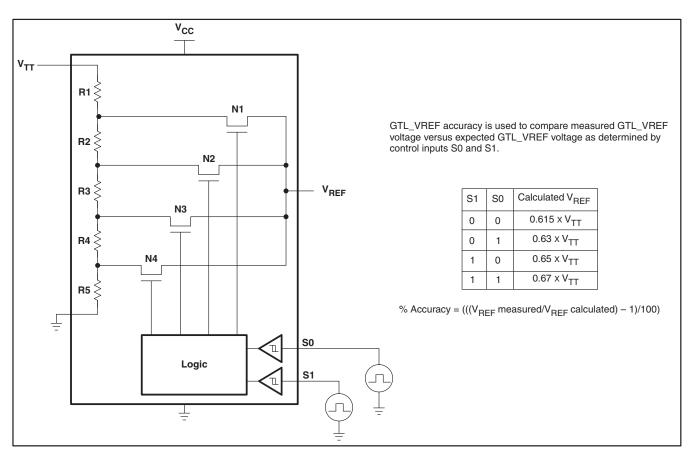


Figure 1. GTL\_REF Accuracy



## PACKAGE OPTION ADDENDUM

6-Feb-2020

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74GTL3004DCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	2TK	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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## PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
		Overall width of the carrier tape
Γ	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74GTL3004DCKR	SC70	DCK	6	3000	180.0	9.2	2.3	2.55	1.2	4.0	8.0	Q3

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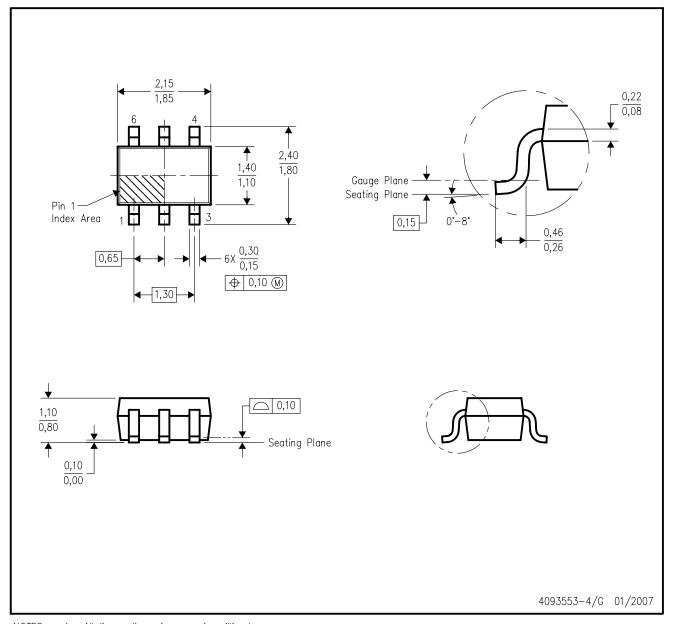


#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74GTL3004DCKR	SC70	DCK	6	3000	205.0	200.0	33.0	

# DCK (R-PDSO-G6)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AB.



# DCK (R-PDSO-G6)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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